

In the specification:

Please replace the paragraph beginning at page 7, line 19, with the following rewritten paragraph:

The second pivoted lever 12 is not carried along “passively” by the first lever 10, but instead is subject to being driven with a predetermined gear ratio relative to the first lever 10 and in the opposite direction to the direction of pivoting of the first lever 10. In accordance with the example shown, this drive is produced by means of a toothed belt 6 which loops around a fixed toothed wheel 5 coaxial to the shaft 4 and a toothed wheel 7 fitted onto the shaft 14 (instead of the toothed belt 6, an intermediate toothed wheel 50 mounted on the first lever 10, which meshes with the toothed wheels 5 and 7, as shown in Fig. 7, could be provided). In this way the pivoting movements of the two levers 10 and 12 (pivoting angles φ_1 and φ_2) are coupled together in a particular way.

Please replace the paragraph beginning at page 10, line 21, with the following rewritten paragraph:

Fig. 8 shows an embodiment of a semiconductor mounting apparatus according to the invention, wherein the toothed belt is replaced by an intermediate toothed wheel 50. Each chip 30 undergoes a rotation of 120° along the path from A to B. The wafer 35 must therefore correspondingly be orientated with the edges of the chip parallel and perpendicular to Ea, and also the displacements of the wafer table 34 must naturally be orientated as shown by the arrows in Fig. 5.